



SM SERIES

3 to 5kV, 270 to 900mA, 65nS Surface Mount Diodes



Features

- J Lead or Gullwing Package Option
- Fast Reverse Recovery Time for High Efficiency
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

Specifications¹

Part Number	V _{RRM} V	I _{FAVM1} 2 mA	I _{FAVM2} 2 mA	V _F V	l _R μΑ	I _{FSM} A	C _J pF	T _{RR} ² nS	R _{θJL} °C/W
J Lead Subseries (Figure 1)									
SM3F	3000	900	350	3.7	0.5	10	6	65	27
SM5F	5000	270	-	5.7	0.5	10	8	65	27
Gullwing Subseries (Figure 2)									
SM3FG	3000	900	350	3.7	0.5	10	6	65	27
SM5FG	5000	270	-	5.7	0.5	10	8	65	27

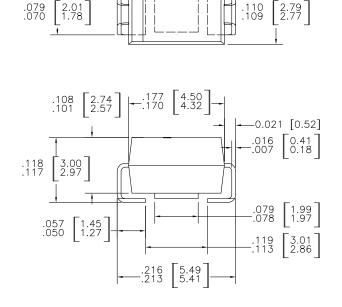
Temperature °C					
Storage Temperature	-55 to 175				
Operating Temperature	-55 to 150				
Maximum Junction Temperature	150				

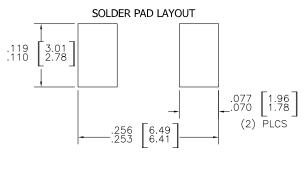
¹25°C ambient temperature unless stated otherwise.

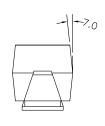
Drawings

Dimensions in inches [mm], tolerances ± 0.020 except as noted

Figure 1







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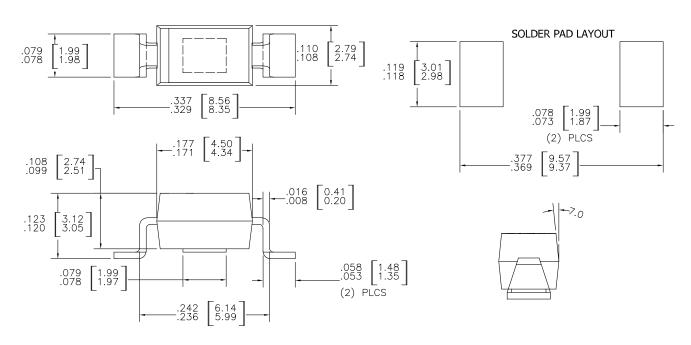
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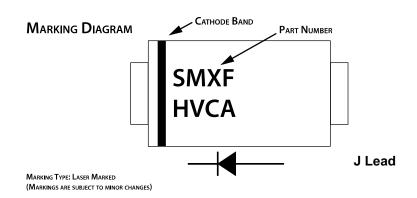
²Check Specification Definitions for conditions details.

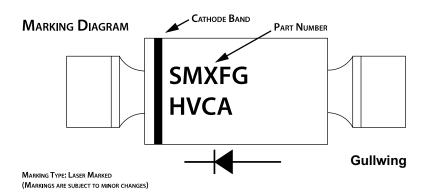


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Figure 2







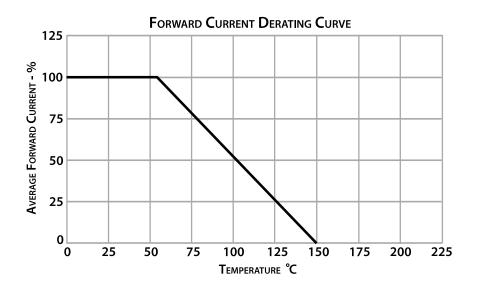
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Specification Definitions

	Specifications	Conditions
V_{RRM}	Maximum Repetitive Reverse Voltage	-
I _{FAVM1}	Maximum Average Forward Current	At T _L = 55°C
I _{FAVM2}	Maximum Average Forward Current	At $T_L = 100$ °C
V_{F}	Maximum Forward Voltage Drop	At I _F = 100mA
I_R	Maximum Leakage Current	At V _{RRM}
I _{FSM}	Maximum Surge Current	At 8.3 mS, Single Half Sine
CJ	Typical Junction Capacitance	At $V_R = 0$ VDC, $f = 1$ MHz
T _{RR}	Maximum Reverse Recovery Time	$I_F = 0.5 I_{FAVM1}$; $I_R = -I_{FAVM1}$; $I_{RR} = -0.25 I_{FAVM1}$ (SM3G,SM3FG) $I_F = 40$ mA; $I_R = -80$ mA; $I_{RR} = -20$ mA (SM5G,SM5FG)
$R_{\theta JL}$	Typical Thermal Resistance	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads

ROHS

Note: Specifications subject to change without notice. Photo is representation only.

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